KSDT

KOREAN INTERNATIONAL SEMICONDUCTOR CONFERENCE & EXHIBITION
ON MANUFACTURING TECHNOLOGY 2024

KISM 2024 BUSAN

November 11 (Mon.) - 15 (Fri.), 2024
Paradise Hotel Busan & Grand Josun Busan
(Haeundae Beach) | Busan, Korea

3N Team

<table>
<tr><td>Company Name</td><td>AP SYSTEMS</td><td>Company Logo</td></tr>
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Hwaseong-Si,Kyunggi-Do,
18487, Korea</td><td rowspan="6">AP Systems</td></tr>
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<tr><td>Exhibitor Introduction</td><td colspan="2">Since our incorporation back in 1994, AP Systems has focused its efforts on R&D activities and business expansion to accomplish continued growth and global market leadership.
Starting with the semiconductor equipment control software business, we made bold moves into the equipment business, integrating Thermal Process, Laser Application, Advanced Package. This has enabled us to expand not only into Semiconductor manufacturing equipment but also into cutting-edge facilities for Secondary Battery and Solar Energy, establishing a stable business and product lineup.</td></tr>
<tr><td>Exhibit Description</td><td colspan="2">Sputter
AP Systems supplies sputtering equipment for the production of metal films (CPB UBM, RDL) to customers in line with the advancements in semiconductor packaging technology.

Advanced Pakage
It is manufacturing process equipment that separates device substrates and carrier substrates using laser, optical technology, and process modules in semiconductor HBM / WLP / PLP manufacturing processes.

Additionally, the latest technology of AP system will be promoted through our booth</td></tr>
<tr><td>Exhibit Product</td><td colspan="2">1. Sputter / FoWLP + RF SPT
2. Advanced Pakage
- Laser Debonder / Blade Dicing / Laser Dicing</td></tr>
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